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APPLICATION NO.	APPLICATION NO. FILING DATE		FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/728,811	12/08/2003		Geum-Jong Bae	239/161 DIV	9264
	7590	05/21/2004		EXAMINER	
LEE & STI SUITE 2000	ERBA, P.C.		HOGANS, DAVID L		
1101 WILSO	ON BOULEVA		ART UNIT	PAPER NUMBER	
ARLINGTO	N, VA 2220	9		2813	4.

DATE MAILED: 05/21/2004

Please find below and/or attached an Office communication concerning this application or proceeding.

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	Application No.	Applicant(s)	
	10/728,811	BAE ET AL	·
Office Action Summary	Examiner	Art Unit	
	David L. Hogans	2813	
The MAILING DATE of this communication a Period for Reply	ppears on the cover sheet w	ith the correspond nc add	lress
	N V IC CET TO EVENE A A	AONTH(C) EDOM	
A SHORTENED STATUTORY PERIOD FOR REP THE MAILING DATE OF THIS COMMUNICATION - Extensions of time may be available under the provisions of 37 CFR after SIX (6) MONTHS from the mailing date of this communication. - If the period for reply specified above is less than thirty (30) days, a re - If NO period for reply is specified above, the maximum statutory perio- Failure to reply within the set or extended period for reply will, by state Any reply received by the Office later than three months after the mai earned patent term adjustment. See 37 CFR 1.704(b).	I. 1.136(a). In no event, however, may a eply within the statutory minimum of thi d will apply and will expire SIX (6) MO ute, cause the application to become A	reply be timely filed rty (30) days will be considered timely. NTHS from the mailing date of this cor BANDONED (35 U.S.C. § 133).	mmunication
Status			
1) Responsive to communication(s) filed on <u>08</u>	December 2003.		
	nis action is non-final.		
3) Since this application is in condition for allow	vance except for formal mat	ters, prosecution as to the	merits is
closed in accordance with the practice under	r <i>Ex par</i> te Quayle, 1935 C.I	D. 11, 453 O.G. 213.	
Disposition of Claims			*
4)⊠ Claim(s) <u>13-16</u> is/are pending in the applicat	ión		
4a) Of the above claim(s) is/are withdi			
5) Claim(s) is/are allowed.	awii nom oonoloorallom		
6)⊠ Claim(s) <u>13-16</u> is/are rejected.			
7) Claim(s) is/are objected to			
8) Claim(s) are subject to restriction and	/or election requirement.		
Application Papers			
9) The specification is objected to by the Exami	nor		
10) ☐ The specification is objected to by the Examination of the Leanning (s) filed on <u>08 December 2003</u> is		☐ objected to by the Exam	iner.
Applicant may not request that any objection to the	·		
Replacement drawing sheet(s) including the corre	the state of the s	· · · · · · · · · · · · · · · · · · ·	R 1.121(d).
11) The oath or declaration is objected to by the		· · · · · · · · · · · · · · · · · · ·	
Priority under 35 U.S.C. § 119			
12)⊠ Acknowledgment is made of a claim for foreignal All b) Some * c) None of:	gn priority under 35 U.S.C.	§ 119(a)-(d) or (f).	
1. Certified copies of the priority docume	nts have been received.		
2. Certified copies of the priority docume	ents have been received in	Application No. <u>10/103,759</u>	<u>)</u> .
3. Copies of the certified copies of the pr	iority documents have bee	n received in this National S	Stage
application from the International Bure	eau (PCT Rule 17.2(a)).	,	
* See the attached detailed Office action for a li	st of the certified copies no	t received.	
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Attachment(s)	•		
1) Notice of References Cited (PTO-892)		Summary (PTO-413) (s)/Mail Date.	
 2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/0 		Informal Patent Application (PTO	· -152)
Paper No(s)/Mail Date <u>12-08-03</u> .	6) Other: _		

Application/Control Number: 10/728,811

Art Unit: 2813

DETAILED ACTION

Page 2

This Office Action is in response to the Transmittal of New Application filed on December 8, 2003.

Priority

1. Acknowledgment is made of applicant's claim for foreign priority under 35 U.S.C. 119(a)-(d). The certified copy has been filed in parent Application No. 10/103,759, filed on March 25, 2002.

Information Disclosure Statement

2. The information disclosure statement (IDS) submitted on December 8, 2003, is in compliance with the provisions of 37 CFR 1.97, and accordingly, has been considered by the examiner.

Claim Rejections - 35 USC § 103

- 3. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
 - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 4. Claims 13-16 are rejected under 35 U.S.C. 103(a) as being unpatentable over 6,506,650 to Yu in view of 6,440,875 to Chan et al. further in view of Microchip

 Fabrication A Practical Guide to Semiconductor Processing (2000) to Van Zant.

Claim 13

Application/Control Number: 10/728,811

Art Unit: 2813

Yu teaches a gate pattern (16) formed on a semiconductor substrate (12); an L-shaped second spacer (28) having a horizontal protruding portion, the second spacer being formed on a sidewall surface of the gate pattern; an L-shaped third spacer (26) having a vertical sidewall between a vertical sidewall of the L-shaped second spacer (28) and the gate pattern (16) and a horizontal protruding portion between the protruding portion of the L-shaped second spacer (28) and the substrate (12); a high-depth junction area (42) formed in the substrate beyond the L-shaped second spacer; a low-depth junction area (44) formed in the substrate under the horizontal protruding portion of the L-shaped second spacer; and a medium-depth junction area (between areas 42 and 44) positioned between the high and low depth junction areas. The Examiner notes that Yu also teaches that implantation depth is controlled by the geometry of the L-shaped spacer. (See Figures 1-6 and columns 2-4 lines 65-45)

Yu fails to explicitly teach wherein the L-shaped spacers are third and fourth spacers and that the high/medium/low depth junctions display corresponding concentration profiles.

However, Chan et al., in Figures 1-6 and columns 3-10 lines 40-17, teaches wherein third and fourth spacer layers are used to construct a graded source/drain structure. Additionally, Van Zant, on pages 348-349, teaches wherein an ion implantation profile follows a gaussian distribution.

Application/Control Number: 10/728,811

Art Unit: 2813

Initially the Examiner notes that it is without moment as to whether the spacer layers are second and third or third and fourth because the concept of graded implantation holds regardless of the number assigned to the layer. Furthermore, it would have been obvious to one of ordinary skill in the art to modify Yu by incorporating a third and fourth spacer layer, as taught by Chan et al., to enhance dimensional control.

Finally, it would have been obvious to one of ordinary skill in the art to modify Yu by incorporating high/medium/low concentration junctions, as taught by Van Zant, because ion implantation profiles follow a gaussian distribution, which shows that implant concentration increases to a finite depth and then diminishes thereafter. The Examiner notes that the nested L-shaped spacer layers of Yu would prevent implantation of many molecules into the medium concentration junction area, as well as, shift the concentration distribution because the nested L-shaped spacer layers add depth to the ion implanted gaussian distribution.

Additionally, the specification contains no disclosure of either the critical nature of the claimed arrangement (i.e. – third and fourth spacer layers) or any unexpected results arising therefrom. Where patentability is said to be based upon particular chosen limitations or upon another variable recited in a claim, the Applicant must show that the chosen limitations are critical. *In re Woodruff*, 919 F.2d 1575, 1578 (Fed. Cir. 1990)

Art Unit: 2813

Claim 14

Incorporating all arguments of Claim 13 and noting that Yu, Chan et al. and Van. Zant teach wherein the medium and low concentration junction areas are formed under the protruding portion of the L-shaped third spacer. (See Yu at Figures 1-6 and columns 2-4 lines 65-45; Chan et al. at Figures 1-6 and columns 3-10 lines 40-17; and Van Zant at pages 348-349)

Claims 15 and 16

Incorporating all arguments of Claim 13 and noting that Yu teaches wherein the L-shaped third/fourth spacer is made of silicon oxide and wherein the L-shaped second/third spacer is made of material having an etch selectivity with respect to the L-shaped fourth spacer (i.e. – a nitride material). (See Yu at Figures 1-6 and columns 2-4 lines 65-45)

Further the Examiner notes that Chan et al. teaches wherein the L-shaped fourth spacer is made of silicon oxide and wherein the L-shaped third spacer is made of material having an etch selectivity with respect to the L-shaped fourth spacer. (See Chan et al. at Figures 1-6 and columns 3-10 lines 40-17)

Conclusion

5. The prior art made of record and not relied upon is considered pertinent to applicant's disclosure.

US 6,153,483 to Yeh et al. teaches wherein a high/medium/low implantation is performed through first and second sidewall spacers and wherein deep source/drain regions are heavily doped and medium to low source/drain regions are lightly doped.

US 5,770,508 to Yeh et al. teaches wherein high/medium/low implantation is performed through first and second sidewall spacers.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to David L. Hogans whose telephone number is (571) 272-1691. The examiner can normally be reached on M-F (7:30-4:30).

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Carl Whitehead Jr. can be reached on (571) 272-1702. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

dh DA

CARL WHITEHEAD, JR.
SUPERMSORY PATENT EXAMINER
TECHNOLOGY CENTER 2800